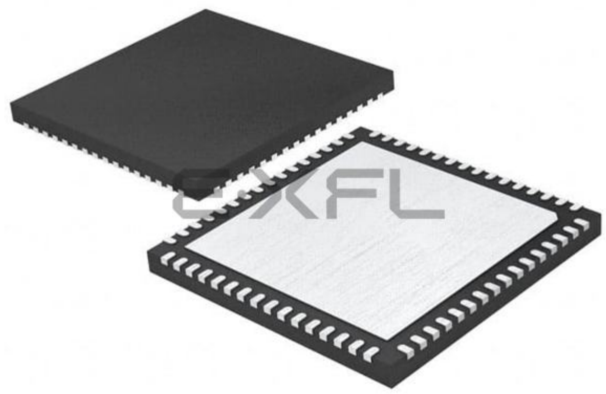
Microchip Technology - DSPIC33EP64MC506T-I/MR Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

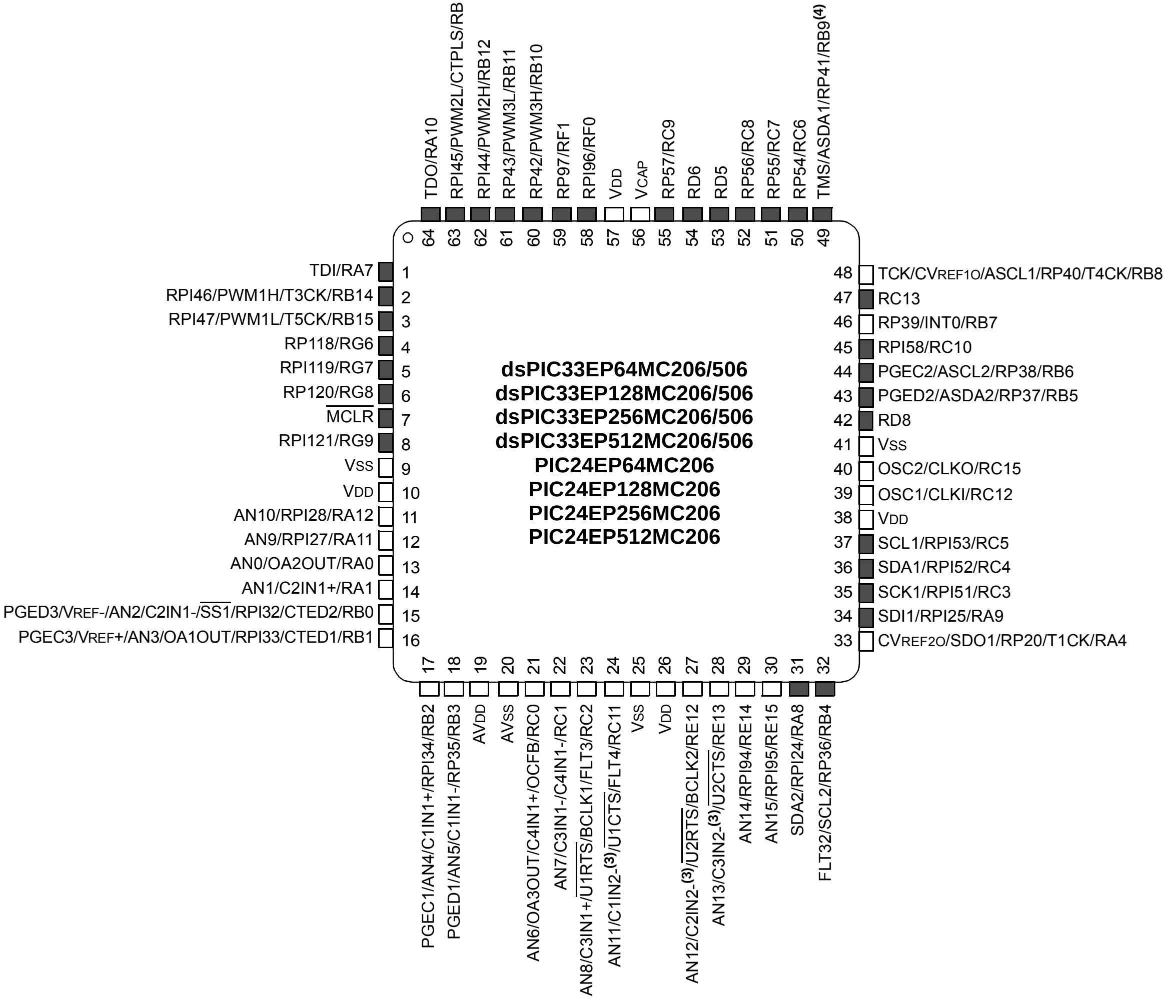
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep64mc506t-i-mr

Pin Diagrams (Continued)

64-Pin TQFP[1,2,3]

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 2-7: INTERLEAVED PFC

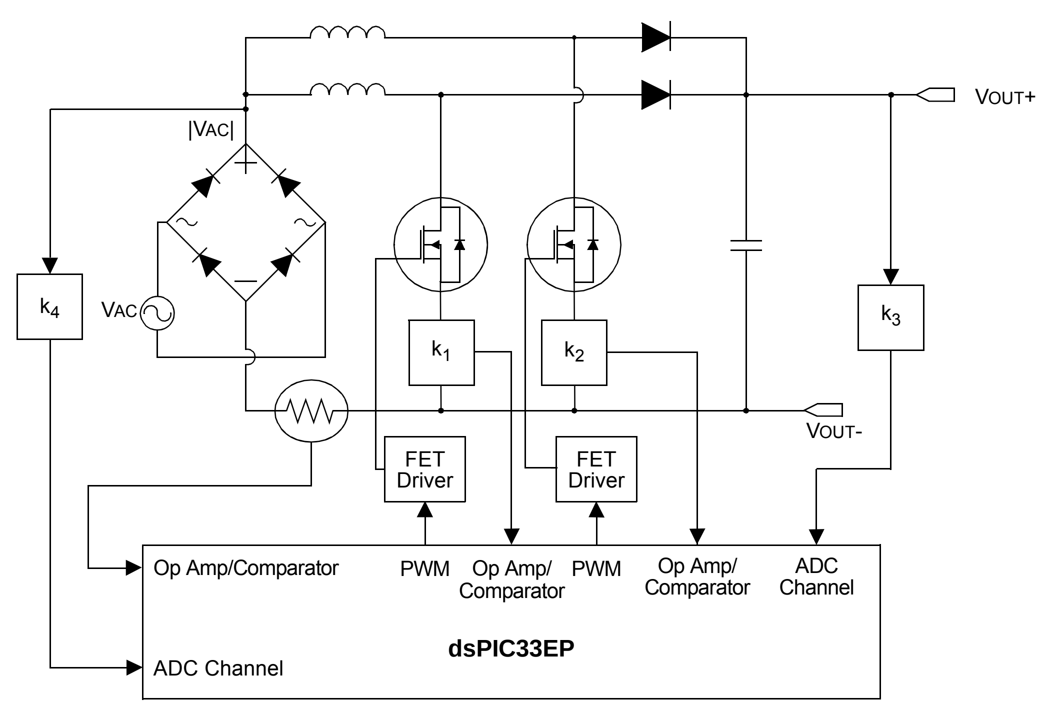
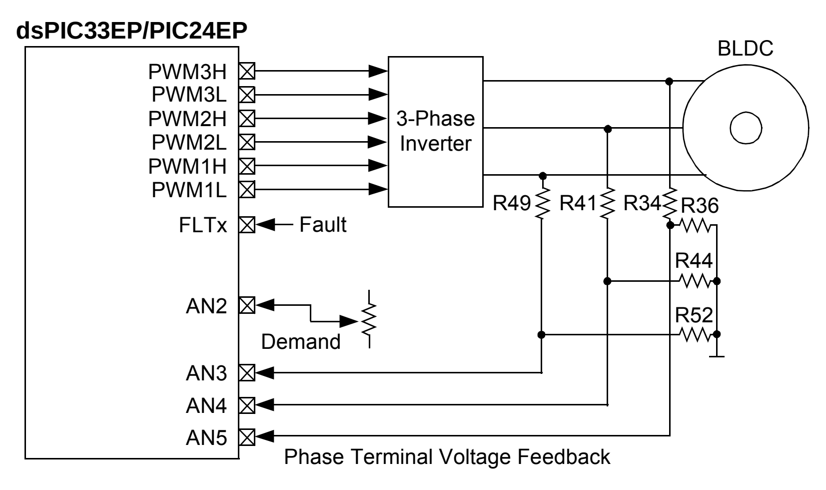


FIGURE 2-8: BEMF VOLTAGE MEASURED USING THE ADC MODULE



REGISTER 3-1: SR: CPU STATUS REGISTER (CONTINUED)

bit 7-5	**IPL<2:0>:** CPU Interrupt Priority Level Status bits(2,3) `111` = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled `110` = CPU Interrupt Priority Level is 6 (14) `101` = CPU Interrupt Priority Level is 5 (13) `100` = CPU Interrupt Priority Level is 4 (12) `011` = CPU Interrupt Priority Level is 3 (11) `010` = CPU Interrupt Priority Level is 2 (10) `001` = CPU Interrupt Priority Level is 1 (9) `000` = CPU Interrupt Priority Level is 0 (8)
bit 4	**RA:** REPEAT Loop Active bit `1` = REPEAT loop in progress `0` = REPEAT loop not in progress
bit 3	**N:** MCU ALU Negative bit `1` = Result was negative `0` = Result was non-negative (zero or positive)
bit 2	**OV:** MCU ALU Overflow bit This bit is used for signed arithmetic (2's complement). It indicates an overflow of the magnitude that causes the sign bit to change state. `1` = Overflow occurred for signed arithmetic (in this arithmetic operation) `0` = No overflow occurred
bit 1	**Z:** MCU ALU Zero bit `1` = An operation that affects the Z bit has set it at some time in the past `0` = The most recent operation that affects the Z bit has cleared it (i.e., a non-zero result)
bit 0	**C:** MCU ALU Carry/$\overline{\text{Borrow}}$ bit `1` = A carry-out from the Most Significant bit of the result occurred `0` = No carry-out from the Most Significant bit of the result occurred

Note 1: This bit is available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL, if IPL<3> = `1`. User interrupts are disabled when IPL<3> = `1`.

3: The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = `1`.

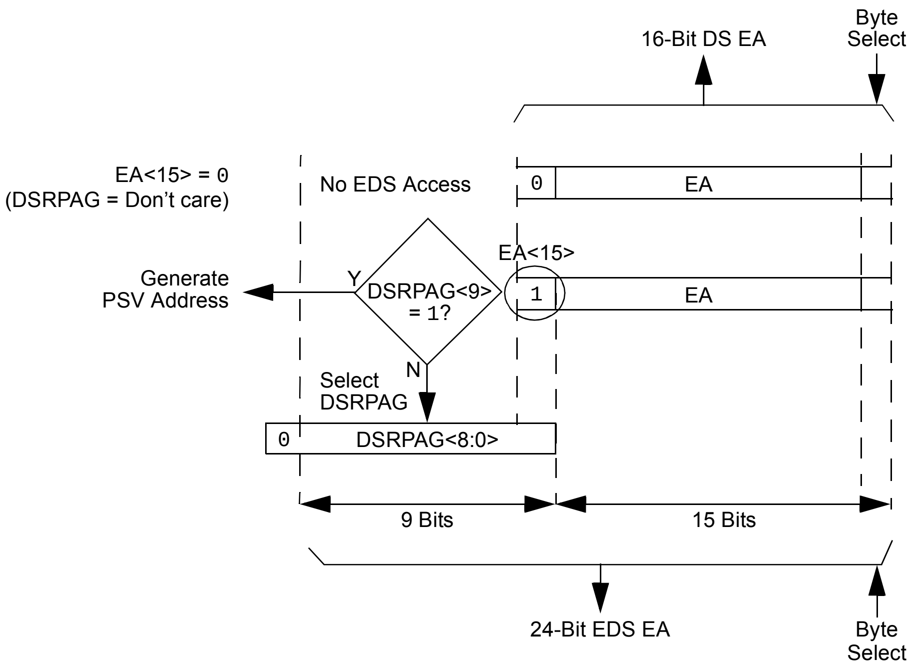
4: A data write to the SR register can modify the SA and SB bits by either a data write to SA and SB or by clearing the SAB bit. To avoid a possible SA or SB bit write race condition, the SA and SB bits should not be modified using bit operations.

4.4.1 PAGED MEMORY SCHEME

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X architecture extends the available Data Space through a paging scheme, which allows the available Data Space to be accessed using `MOV` instructions in a linear fashion for pre-modified and post-modified Effective Addresses (EA). The upper half of the base Data Space address is used in conjunction with the Data Space Page registers, the 10-bit Read Page register (DSRPAG) or the 9-bit Write Page register (DSWPAG), to form an Extended Data Space (EDS) address or Program Space Visibility (PSV) address. The Data Space Page registers are located in the SFR space.

Construction of the EDS address is shown in Example 4-1. When DSRPAG<9> = `0` and the base address bit, EA<15> = `1`, the DSRPAG<8:0> bits are concatenated onto EA<14:0> to form the 24-bit EDS read address. Similarly, when base address bit, EA<15> = `1`, DSWPAG<8:0> are concatenated onto EA<14:0> to form the 24-bit EDS write address.

EXAMPLE 4-1: EXTENDED DATA SPACE (EDS) READ ADDRESS GENERATION



Note: DS read access when DSRPAG = 0x000 will force an address error trap.

10.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Watchdog Timer and Power-Saving Modes"** (DS70615) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of peripherals being clocked constitutes lower consumed power.

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices can manage power consumption in four ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software-Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices have two special power-saving modes that are entered through the execution of a special `PWRSAV` instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the `PWRSAV` instruction is shown in Example 10-1.

Note: `SLEEP_MODE` and `IDLE_MODE` are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

EXAMPLE 10-1: `PWRSAV` INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into Sleep mode
PWRSAV  #IDLE_MODE     ; Put the device into Idle mode
```

REGISTER 10-3: PMD3: PERIPHERAL MODULE DISABLE CONTROL REGISTER 3

U-0	U-0	U-0	U-0	U-0	R/W-0	U-0	U-0
—	—	—	—	—	CMPMD	—	—
bit 15							bit 8

R/W-0	U-0	U-0	U-0	U-0	U-0	R/W-0	U-0
CRCMD	—	—	—	—	—	I2C2MD	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as ‘0’

bit 10 **CMPMD:** Comparator Module Disable bit
1 = Comparator module is disabled
0 = Comparator module is enabled

bit 9-8 **Unimplemented:** Read as ‘0’

bit 7 **CRCMD:** CRC Module Disable bit
1 = CRC module is disabled
0 = CRC module is enabled

bit 6-2 **Unimplemented:** Read as ‘0’

bit 1 **I2C2MD:** I2C2 Module Disable bit
1 = I2C2 module is disabled
0 = I2C2 module is enabled

bit 0 **Unimplemented:** Read as ‘0’

REGISTER 10-4: PMD4: PERIPHERAL MODULE DISABLE CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0	U-0
—	—	—	—	REFOMD	CTMUMD	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as ‘0’

bit 3 **REFOMD:** Reference Clock Module Disable bit
1 = Reference clock module is disabled
0 = Reference clock module is enabled

bit 2 **CTMUMD:** CTMU Module Disable bit
1 = CTMU module is disabled
0 = CTMU module is enabled

bit 1-0 **Unimplemented:** Read as ‘0’

11.0 I/O PORTS

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"I/O Ports"** (DS70598) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

Many of the device pins are shared among the peripherals and the parallel I/O ports. All I/O input ports feature Schmitt Trigger inputs for improved noise immunity.

11.1 Parallel I/O (PIO) Ports

Generally, a parallel I/O port that shares a pin with a peripheral is subservient to the peripheral. The peripheral's output buffer data and control signals are provided to a pair of multiplexers. The multiplexers select whether the peripheral or the associated port has ownership of the output data and control signals of the I/O pin. The logic also prevents "loop through," in which a port's digital output can drive the input of a peripheral that shares the same pin. Figure 11-1 illustrates how ports are shared with other peripherals and the associated I/O pin to which they are connected.

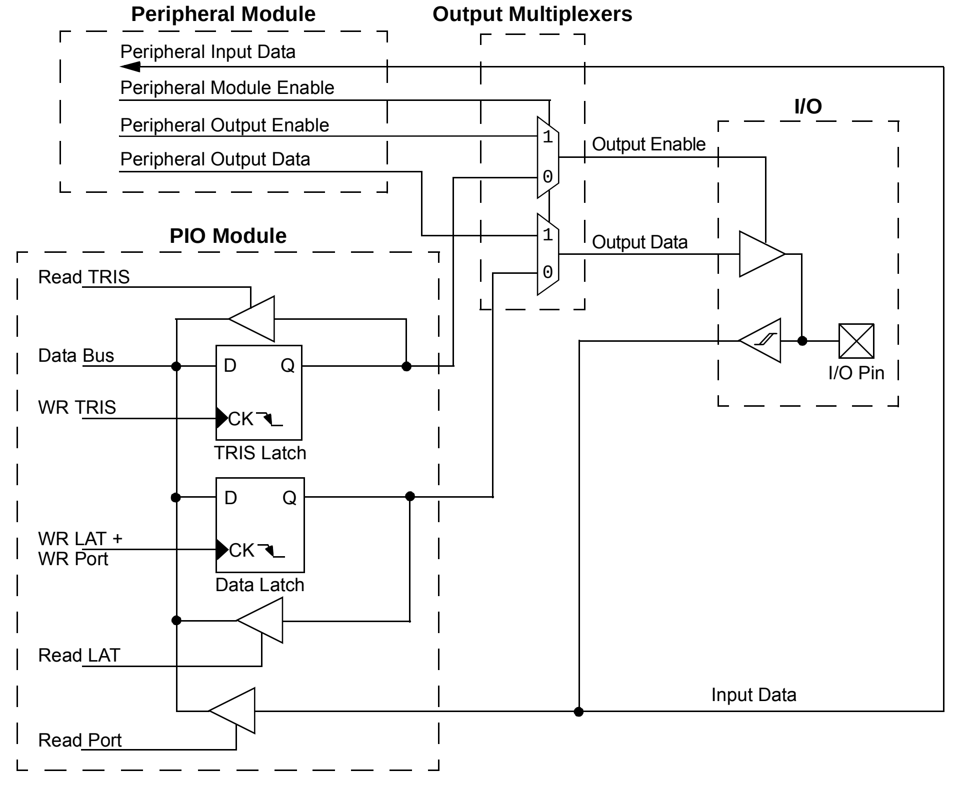
When a peripheral is enabled and the peripheral is actively driving an associated pin, the use of the pin as a general purpose output pin is disabled. The I/O pin can be read, but the output driver for the parallel port bit is disabled. If a peripheral is enabled, but the peripheral is not actively driving a pin, that pin can be driven by a port.

All port pins have eight registers directly associated with their operation as digital I/O. The Data Direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the Latch register (LATx) read the latch. Writes to the Latch write the latch. Reads from the port (PORTx) read the port pins, while writes to the port pins write the latch.

Any bit and its associated data and control registers that are not valid for a particular device is disabled. This means the corresponding LATx and TRISx registers and the port pin are read as zeros.

When a pin is shared with another peripheral or function that is defined as an input only, it is nevertheless regarded as a dedicated port because there is no other competing source of outputs.

FIGURE 11-1: BLOCK DIAGRAM OF A TYPICAL SHARED PORT STRUCTURE



NOTES:

REGISTER 15-2: OCxCON2: OUTPUT COMPARE x CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0
FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32
bit 15							bit 8

R/W-0	R/W-0, HS	R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0
OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **FLTMD:** Fault Mode Select bit
`1` = Fault mode is maintained until the Fault source is removed; the corresponding OCFLTx bit is cleared in software and a new PWM period starts
`0` = Fault mode is maintained until the Fault source is removed and a new PWM period starts

bit 14 **FLTOUT:** Fault Out bit
`1` = PWM output is driven high on a Fault
`0` = PWM output is driven low on a Fault

bit 13 **FLTTRIEN:** Fault Output State Select bit
`1` = OCx pin is tri-stated on a Fault condition
`0` = OCx pin I/O state is defined by the FLTOUT bit on a Fault condition

bit 12 **OCINV:** Output Compare x Invert bit
`1` = OCx output is inverted
`0` = OCx output is not inverted

bit 11-9 **Unimplemented:** Read as ‘`0`’

bit 8 **OC32:** Cascade Two OCx Modules Enable bit (32-bit operation)
`1` = Cascade module operation is enabled
`0` = Cascade module operation is disabled

bit 7 **OCTRIG:** Output Compare x Trigger/Sync Select bit
`1` = Triggers OCx from the source designated by the SYNCSELx bits
`0` = Synchronizes OCx with the source designated by the SYNCSELx bits

bit 6 **TRIGSTAT:** Timer Trigger Status bit
`1` = Timer source has been triggered and is running
`0` = Timer source has not been triggered and is being held clear

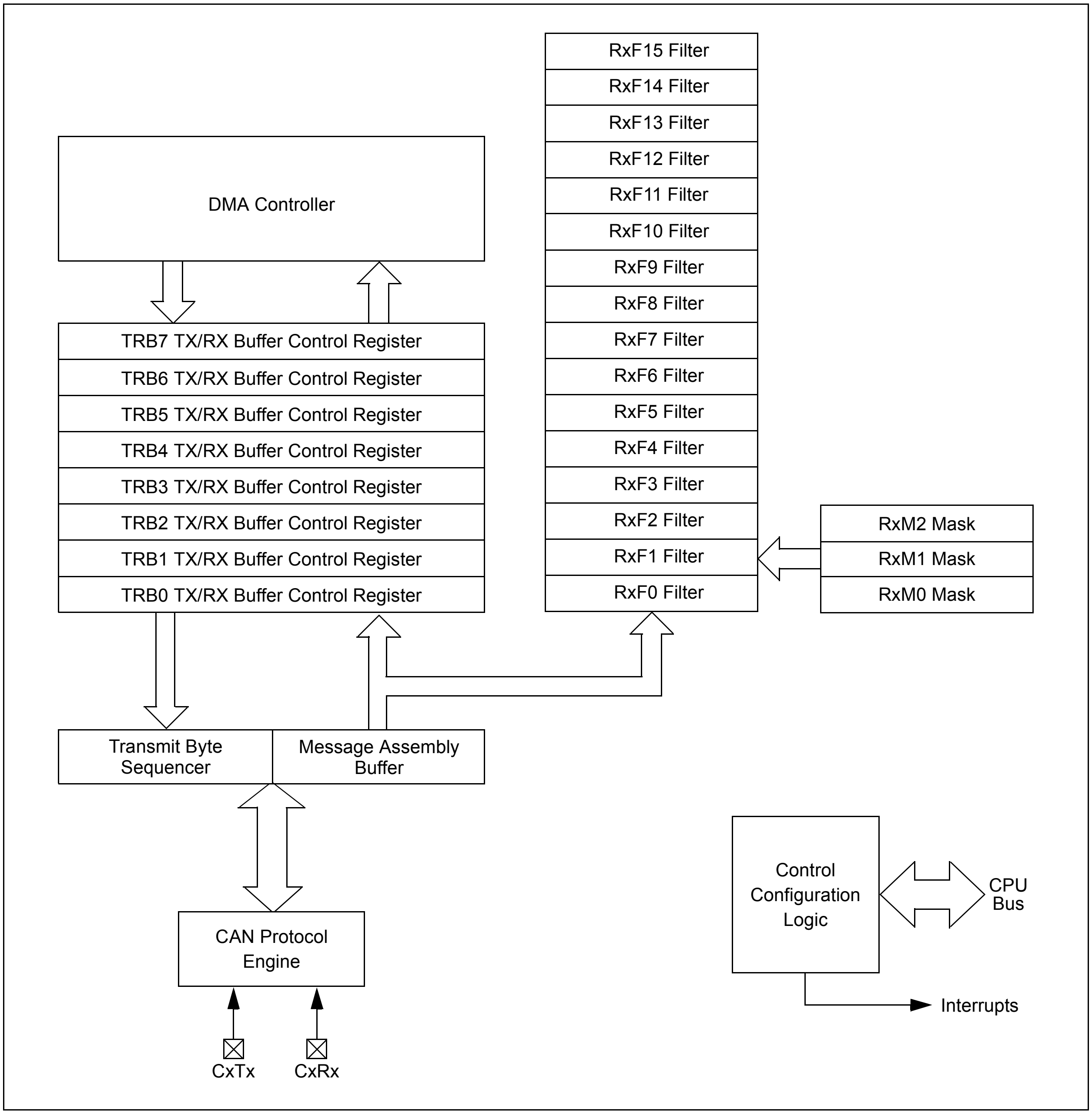
bit 5 **OCTRIS:** Output Compare x Output Pin Direction Select bit
`1` = OCx is tri-stated
`0` = Output Compare x module drives the OCx pin

Note 1: Do not use the OCx module as its own Synchronization or Trigger source.

2: When the OCy module is turned OFF, it sends a trigger out signal. If the OCx module uses the OCy module as a Trigger source, the OCy module must be unselected as a Trigger source prior to disabling it.

3: Each Output Compare x module (OCx) has one PTG Trigger/Synchronization source. See **Section 24.0 “Peripheral Trigger Generator (PTG) Module”** for more information.
PTGO0 = OC1
PTGO1 = OC2
PTGO2 = OC3
PTGO3 = OC4

FIGURE 21-1: ECAN™ MODULE BLOCK DIAGRAM



NOTES:

24.3 PTG Control Registers

REGISTER 24-1: PTGCST: PTG CONTROL/STATUS REGISTER

R/W-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
PTGEN	—	PTGSIDL	PTGTOGL	—	PTGSWT[2]	PTGSSEN[3]	PTGIVIS
bit 15							bit 8

R/W-0	HS-0	U-0	U-0	U-0	U-0	R/W-0	
PTGSTRT	PTGWDTO	—	—	—	—	PTGITM1[1]	PTGITM0[1]
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **PTGEN:** Module Enable bit

1 = PTG module is enabled
0 = PTG module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **PTGSIDL:** PTG Stop in Idle Mode bit

1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **PTGTOGL:** PTG TRIG Output Toggle Mode bit

1 = Toggle state of the PTGOx for each execution of the `PTGTRIG` command
0 = Each execution of the `PTGTRIG` command will generate a single PTGOx pulse determined by the value in the PTGPWDx bits

bit 11 **Unimplemented:** Read as ‘0’

bit 10 **PTGSWT:** PTG Software Trigger bit[2]

1 = Triggers the PTG module
0 = No action (clearing this bit will have no effect)

bit 9 **PTGSSEN:** PTG Enable Single-Step bit[3]

1 = Enables Single-Step mode
0 = Disables Single-Step mode

bit 8 **PTGIVIS:** PTG Counter/Timer Visibility Control bit

1 = Reads of the PTGSDLIM, PTGCxLIM or PTGTxLIM registers return the current values of their corresponding counter/timer registers (PTGSD, PTGCx, PTGTx)
0 = Reads of the PTGSDLIM, PTGCxLIM or PTGTxLIM registers return the value previously written to those limit registers

bit 7 **PTGSTRT:** PTG Start Sequencer bit

1 = Starts to sequentially execute commands (Continuous mode)
0 = Stops executing commands

bit 6 **PTGWDTO:** PTG Watchdog Timer Time-out Status bit

1 = PTG Watchdog Timer has timed out
0 = PTG Watchdog Timer has not timed out.

bit 5-2 **Unimplemented:** Read as ‘0’

Note 1: These bits apply to the `PTGWHI` and `PTGWLO` commands only.
2: This bit is only used with the `PTGCTRL` step command software trigger option.
3: Use of the PTG Single-Step mode is reserved for debugging tools only.

27.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection and CodeGuard™ Security
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation

27.1 Configuration Bits

In dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, the Configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored in at the top of the on-chip program memory space, known as the Flash Configuration bytes. Their specific locations are shown in Table 27-1. The configuration data is automatically loaded from the Flash Configuration bytes to the proper Configuration Shadow registers during device Resets.

Note: Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration bytes for configuration data in their code for the compiler. This is to make certain that program code is not stored in this address when the code is compiled.

The upper 2 bytes of all Flash Configuration Words in program memory should always be '`1111 1111 1111 1111`'. This makes them appear to be `NOP` instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '`1`'s to these locations has no effect on device operation.

Note: Performing a page erase operation on the last page of program memory clears the Flash Configuration bytes, enabling code protection as a result. Therefore, users should avoid performing page erase operations on the last page of program memory.

The Configuration Flash bytes map is shown in Table 27-1.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
	IIL	**Input Leakage Current[1,2]**					
DI50		I/O Pins 5V Tolerant[3]	-1	—	+1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		I/O Pins Not 5V Tolerant[3]	-1	—	+1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +85°C
DI51a		I/O Pins Not 5V Tolerant[3]	-1	—	+1	µA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +85°C
DI51b		I/O Pins Not 5V Tolerant[3]	-1	—	+1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +125°C
DI51c		I/O Pins Not 5V Tolerant[3]	-1	—	+1	µA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +125°C
DI55		$\overline{\text{MCLR}}$	-5	—	+5	µA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	-5	—	+5	µA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: VIL source < (VSS – 0.3). Characterized but not tested.

5: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 30-11: TIMERQ (QEI MODULE) EXTERNAL CLOCK TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

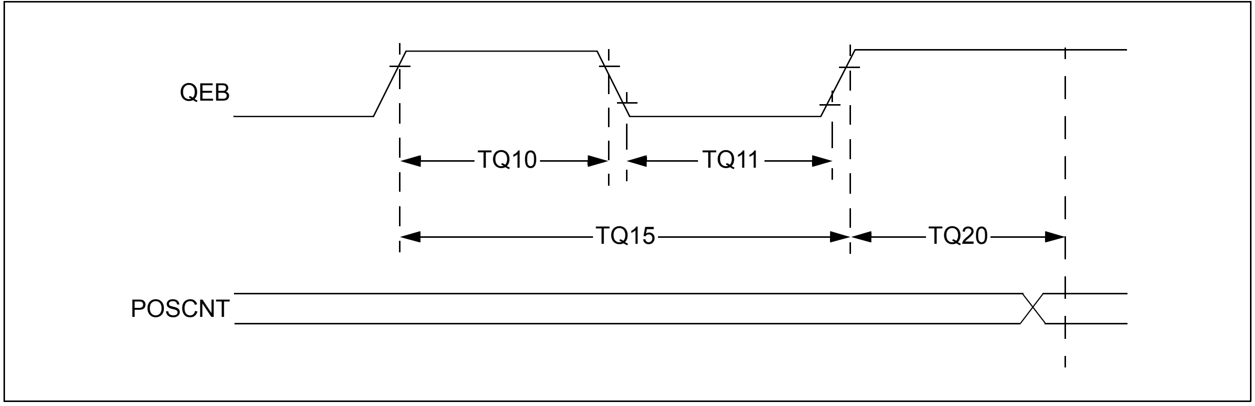


TABLE 30-30: QEI MODULE EXTERNAL CLOCK TIMING REQUIREMENTS (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS				**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**[1]		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TQ10	TtQH	TQCK High Time	Synchronous, with prescaler	Greater of 12.5 + 25 or (0.5 TCY/N) + 25	—	—	ns	Must also meet Parameter TQ15
TQ11	TtQL	TQCK Low Time	Synchronous, with prescaler	Greater of 12.5 + 25 or (0.5 TCY/N) + 25	—	—	ns	Must also meet Parameter TQ15
TQ15	TtQP	TQCP Input Period	Synchronous, with prescaler	Greater of 25 + 50 or (1 TCY/N) + 50	—	—	ns	
TQ20	TCKEXTMRL	Delay from External TQCK Clock Edge to Timer Increment		—	1	TCY	—	

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 30-29: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS

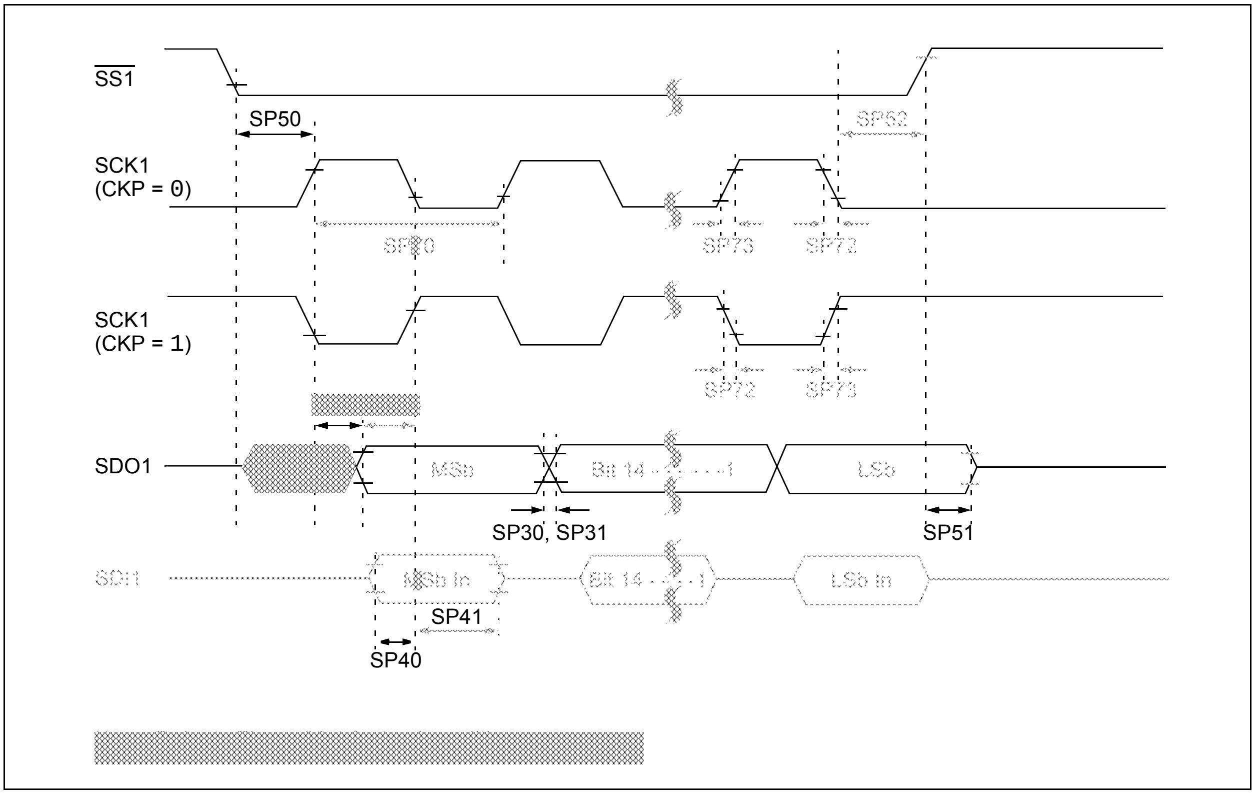


TABLE 30-54: OP AMP/COMPARATOR VOLTAGE REFERENCE SETTLING TIME SPECIFICATIONS

AC CHARACTERISTICS			**Standard Operating Conditions (see Note 2): 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
VR310	T_{SET}	Settling Time	—	1	10	µs	**(Note 1)**

Note 1: Settling time is measured while CVRR = `1` and CVR<3:0> bits transition from ‘`0000`’ to ‘`1111`’.

2: Device is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

TABLE 30-55: OP AMP/COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

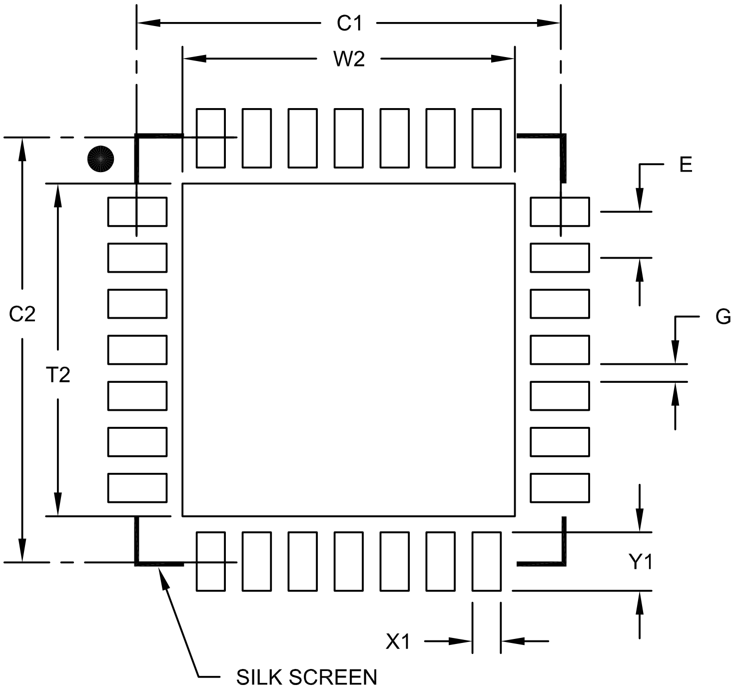
DC CHARACTERISTICS			**Standard Operating Conditions (see Note 1): 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
VRD310	CV_{RES}	Resolution	$CV_{RSRC}/24$	—	$CV_{RSRC}/32$	LSb	
VRD311	CVR_{AA}	Absolute Accuracy(2)	—	±25	—	mV	CV_{RSRC} = 3.3V
VRD313	CV_{RSRC}	Input Reference Voltage	0	—	AV_{DD} + 0.3	V	
VRD314	CVR_{OUT}	Buffer Output Resistance(2)	—	1.5k	—	Ω	

Note 1: Device is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Parameter is characterized but not tested in manufacturing.

28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.70
Optional Center Pad Length	T2			4.70
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.40
Contact Pad Length (X28)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

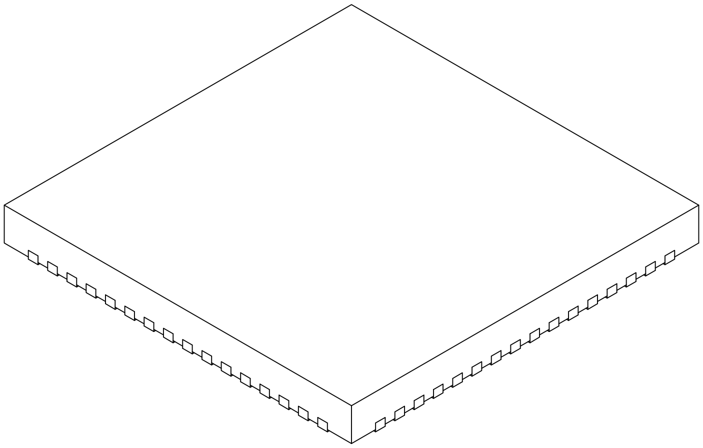
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2124A

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body with 5.40 x 5.40 Exposed Pad [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		64	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		9.00 BSC	
Exposed Pad Width	E2	5.30	5.40	5.50
Overall Length	D		9.00 BSC	
Exposed Pad Length	D2	5.30	5.40	5.50
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

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